

TC2411
14-Bit, 1 GSPS Digital-to-Analog Converter
with Standby Mode of Operation

The TC2411 is a 14-bit, 1 GSPS digital-to-analog converter that delivers exceptional high-frequency performance. The TC2411 is designed to support single or multiple transmit IF signals up to 500 MHz and to deliver superior dynamic range at a sampling rate up to a guaranteed 1 GSPS. A power down feature has been incorporated into the TC2411 which allows the part to be placed into a Standby Mode of operation.

- High resolution
- High Clock rate
- Standby Mode for lower power dissipation

Description

As shown in the functional block diagram below, the TC2411 features a 5-Bit Unary + 9-Bit Binary R2R architecture. 14-bit straight binary data can be input to the DAC at a sample rate of up to 1 GSPS. The DAC provides low-noise and low-spurious performance with digital IF input signals across the first Nyquist band.

The highly linear analog output produced by the TC2411 may be filtered externally to reject the signal image, and is suitable for single-stage upconversion applications.

Applications

The TC2411's high sample rate makes it ideal for the following applications:

- Signal generation
- Direct digital synthesis (DDS)
- Test and measurement
- Software radio
- Single- and multi-carrier transceivers
- Radar (Including Burst mode capability)

Technical Features

- Signal-Noise Ratio.....74dBc @126MHz
- Signal Input.....1000MSPS, 14bits LVDS
- Spur Free Dynamic Range.....75dBc @126MHz
- Clock Input Drive.. 0 to +13dBm, 25Ω differential
- Full Scale Output.....-2dBm, 50Ω differential
- Voltage Reference.....2.5V Bandgap On-Chip
- Power Dissipation1.8W
- Technology0.5 μm SiGe BiCMOS
- Packaging.....96 ball, Pb-free, Cavity-down BGA

Ordering Information

| PART NUMBER | TEMP RANGE (°C) | PACKAGE | CLOCK SPEED |
|-------------------|-----------------------|----------------------------|-----------------|
| TC2411-IB | -40°C to +85°C | 96 ball Pb-free BGA | 1000 MHz |
| TC2411-KIT | +25C | Evaluation Kit | |

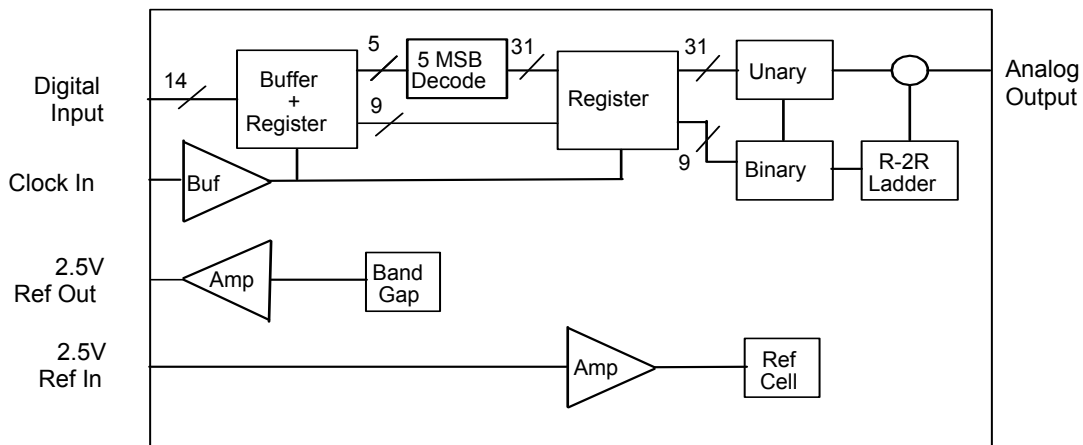


Figure 1: TC2411 Functional Block Diagram

Absolute Maximum Ratings

(Electrical performance is not guaranteed at absolute maximum ratings. Exposure to absolute maximum ratings for an extended period of time may impair the useful life of the product)

| Parameter | Max | Unit |
|-----------------------------------|-------------|-----------------|
| Electrical | | |
| +5.0V Supply Voltage AVCC, DVDD | +5.5 | V |
| +3.3V Supply Voltage DVCC | +3.6 | V |
| -5.0V Supply Voltage AVEE, DVEE | -5.5 | V |
| Clock Input Voltage | +4.0 | V _{pp} |
| Environmental | | |
| Operating Temp Range | -40 to +85 | °C |
| Storage Temp Range | -65 to +150 | °C |
| Maximum Junction Temperature | +110 | °C |
| Reflow Soldering Peak Temperature | +260 | °C |

TC2411 Electrical Specifications

(AVEE, DVEE = -5V; AVCC, DVDD = +5V; DVCC = +3.3V; IOUT = 20 mA, -40°C to +85°C ambient, unless otherwise noted)

| DC SPECIFICATIONS | CONDITION | MIN | TYP | MAX | UNITS |
|----------------------------------|--|-------|------|-------|-------|
| Supply Voltages | | | | | |
| AVCC, DVDD | | 4.75 | 5.0 | 5.25 | V |
| DVCC | | 3.13 | 3.3 | 3.46 | V |
| AVEE | | -5.25 | -5.0 | -4.75 | V |
| DVEE | | -5.25 | -5.0 | -4.75 | V |
| Normal Mode | | | | | |
| AVCC + DVDD + DVCC Current | | | 30 | | mA |
| AVEE + DVEE Current | | | 330 | | mA |
| Power Consumption | | | 1.8 | | W |
| Reference Voltage info | V _{out_REF} | | 2.5 | | V |
| Reference Output Load Regulation | 0 < I _{source} < I _{max} | | | | mV |
| Resolution | | | 14 | | Bits |
| Standby Mode | | | | | |
| AVCC + DVDD + DVCC Current | | | 40 | | mA |
| AVEE + DVEE Current | | | 140 | | mA |
| Power Consumption | | | 850 | | mW |

TC2411 Electrical Specifications continued

(AVEE, DVEE = -5V; AVCC, DVDD = +5V; DVCC = +3.3V; IOOUT = 20 mA, -40°C to +85°C ambient, unless otherwise noted)

| DIGITAL SPECIFICATIONS | CONDITION | MIN | TYP | MAX | UNITS |
|---|-------------|------|------|------|--------------|
| Logic Inputs (N1- N14, P1 – P14) | | | | | |
| Compatibility | LVDS | | | | |
| Input Impedance | | | 100 | | ohms |
| Common Mode Voltage (VCM) | | | +1.2 | | V |
| Differential Input High Level | VCM = +1.2V | | | +100 | mV |
| Differential Input Low Level | VCM = +1.2V | -100 | | | mV |
| Data Coding | Binary | | | | |
| Switching characteristics | | | | | |
| Setup Time | | | 130 | | ps |
| Hold Time | | | 440 | | ps |
| Propagation Delay Time | | | 400 | | ps |
| Data Rise Time | 10% to 90 % | | 220 | | ps |
| Data Fall Time | 90% to 10 % | | 230 | | ps |
| Reset (RST) | | | | | |
| High Level | | | 3.3 | | Volts |
| Low Level | | | 0 | | Volts |
| Pulse Width | | 2.5 | | | ns |
| Pulse Repetition Rate | | DC | | 200 | MHz |
| Propagation Delay | | | 3 | | Clock cycles |
| Standby Mode (SLP, SLN) | | | | | |
| Single Ended Drive | | | | | |
| Low Level | | | 0 | | Volts |
| High Level | | | 3.3 | | Volts |
| Differential drive (External 100Ω) | | | | | |
| Low Level | | | 1.0 | | Volts |
| High Level | | | 1.4 | | Volts |

| ANALOG SPECIFICATIONS | CONDITION | MIN | TYP | MAX | UNITS |
|---------------------------------|-----------------------------------|------|-------|-----|------------------|
| DAC Clock (CLKP, CLKN) | | | | | |
| Maximum Conversion Rate | Guaranteed | 1000 | | | MSPS |
| Differential Input Voltage | | | 1.5 | | V _{pp} |
| Common-mode Input Voltage | | | -3.1 | | V |
| Differential Input Resistance | | | 25 | | ohms |
| Analog Output (VOP, VON) | | | | | |
| Full Scale Output Voltage | 20 mA Differential Output Current | | 0.480 | | V _{p-p} |
| Differential Output Resistance | | | 50 | | ohms |

| DYNAMIC SPECIFICATIONS | CONDITION | MIN | TYP | MAX | UNITS |
|--|----------------------|-----|------|-----|--------|
| DAC Output vs Frequency @ -0.5 dBFS | | | | | |
| $f_{out} = 33 \text{ MHz}$ | | | -3 | | dBm |
| $f_{out} = 126 \text{ MHz}$ | | | -3 | | dBm |
| $f_{out} = 251 \text{ MHz}$ | | | -5 | | dBm |
| $f_{out} = 376 \text{ MHz}$ | | | -8 | | dBm |
| $f_{out} = 490 \text{ MHz}$ | | | -9 | | dBm |
| Noise Spectral Density @ -0.5 dBFS | | | | | |
| $f_{out} = 33 \text{ MHz}$ | | | -166 | | dBm/Hz |
| $f_{out} = 126 \text{ MHz}$ | | | -164 | | dBm/Hz |
| $f_{out} = 251 \text{ MHz}$ | | | -161 | | dBm/Hz |
| $f_{out} = 376 \text{ MHz}$ | | | -161 | | dBm/Hz |
| $f_{out} = 490 \text{ MHz}$ | | | -160 | | dBm/Hz |
| SFDR vs Frequency @ -0.5 dBFS | | | | | |
| $f_{out} = 33 \text{ MHz}$ | | | -78 | | dBc |
| $f_{out} = 126 \text{ MHz}$ | | | -75 | | dBc |
| $f_{out} = 251 \text{ MHz}$ | | | -70 | | dBc |
| $f_{out} = 376 \text{ MHz}$ | | | -65 | | dBc |
| $f_{out} = 490 \text{ MHz}$ | | | -60 | | dBc |
| IMD | | | | | |
| IF = 135 MHz, 145 MHz | 2 Tones @ -6.5 dBFS | | -82 | | dBc |
| IF = 110 MHz, 120 MHz, 130 MHz, 140 MHz | 4 Tones @ -12.5 dBFS | | -82 | | dBc |
| ACPR (EDGE) | | | | | |
| IF = 260 MHz | 1 Tone @ -3.5 dBFS | | -95 | | dBc |
| IF = 230 MHz, 240 MHz, 260 MHz, 270 MHz | 4 Tones @ -15.5 dBFS | | -88 | | dBc |
| ACPR (WCDMA) | | | | | |
| IF = 260 MHz | 1 Tone @ -10.5 dBFS | | -75 | | dBc |
| IF = 230 MHz, 240 MHz, 260 MHz, 270 MHz | 4 Tones @ -17.5 dBFS | | -76 | | dBc |
| Analog Output Response | | | | | |
| Output Settling Time | | | | | pS |
| Output Rise Time (10 - 90%) | | | 220 | | pS |
| Output Fall Time (90 - 10%) | | | 230 | | pS |
| Glitch Energy | | | | | |
| -FS to +FS transition | FS = Full-Scale | | 0.5 | | ps-V |
| +FS to -FS transition | | | 0.1 | | ps-V |
| -MS to +MS transition | MS = Mid-Scale | | 0.4 | | ps-V |
| +MS to -MS transition | | | 0.2 | | ps-V |

TC2411 Thermal Characteristics

Normal Mode of Operation

| Package | θ_{JC} ($^{\circ}C/W$) | θ_{JA} ($^{\circ}C/W$) | | | Note |
|---------------------------|---------------------------------|---------------------------------|------|------|--|
| | | 0 m/s | 2m/s | 3m/s | |
| 19X19 Cavity-down BGA 96L | 2.72 | 20.2 | 18.5 | 17.5 | Results based on FEA simulation without heat sink. |

- The DC power of the TC2411 is 1.8 W in normal mode of operation
- Maximum Junction Temperature is not to exceed 110°C.
- There is no need for an external heat sink if maximum ambient temperature is +70°C.
- An external heat sink is recommended for ambient temperatures in excess of +70°C to insure that the junction temperature does not exceed 110°C maximum.
- Use of standby mode reduces the average power dissipation proportional to the normal mode / standby mode duty cycle and allows a higher ambient temperature before a heat sink must be used to insure that the junction temperature does not exceed 110°C maximum.
- In the above table, θ_{JA} is presented according to JEDEC JESD 51-2 (natural convection) and 51-6 (forced convection). Thermal simulation assumes the package is mounted on the test board specified by JEDEC JESD51-9 (101.6X114.3X1.6 mm, four layers).

Note:

θ_{JC} : Thermal resistance from junction to case.

θ_{JA} : Thermal resistance from junction to ambient.

Figure 2: Standby Mode Operational Truth Table

| <u>Control Signal</u> | <u>Normal Mode</u> | <u>Standby Mode</u> |
|-----------------------|--------------------|---------------------|
| STDBY_P | L | H |
| STDBY_N | H | L |

Figure 3: Standby/Normal Mode Timing

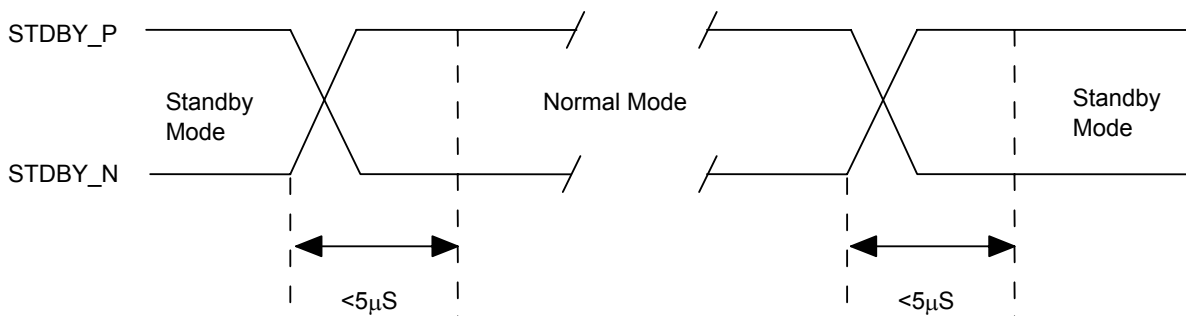


Figure 4: TC2411 Typical Application Circuit

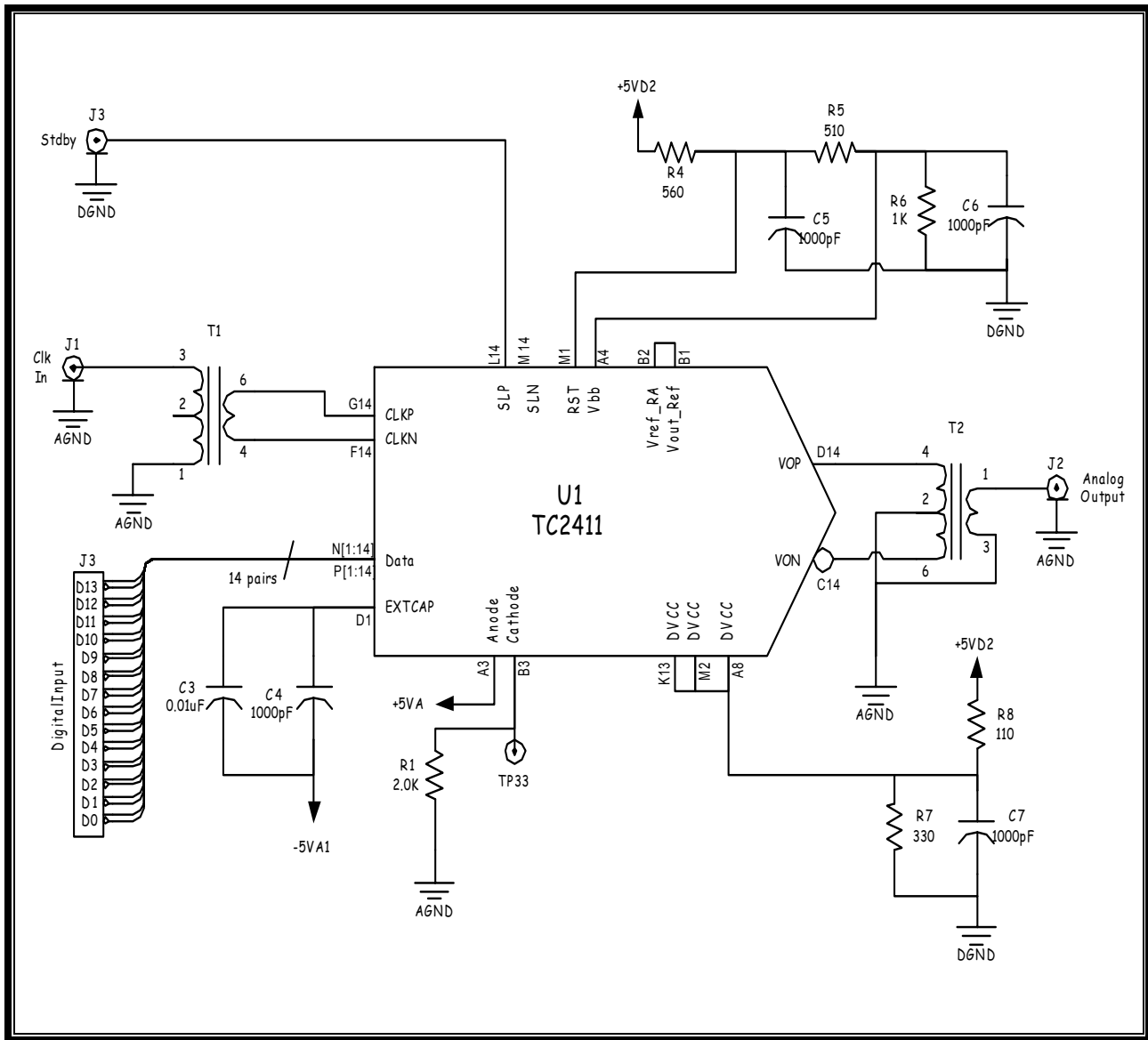
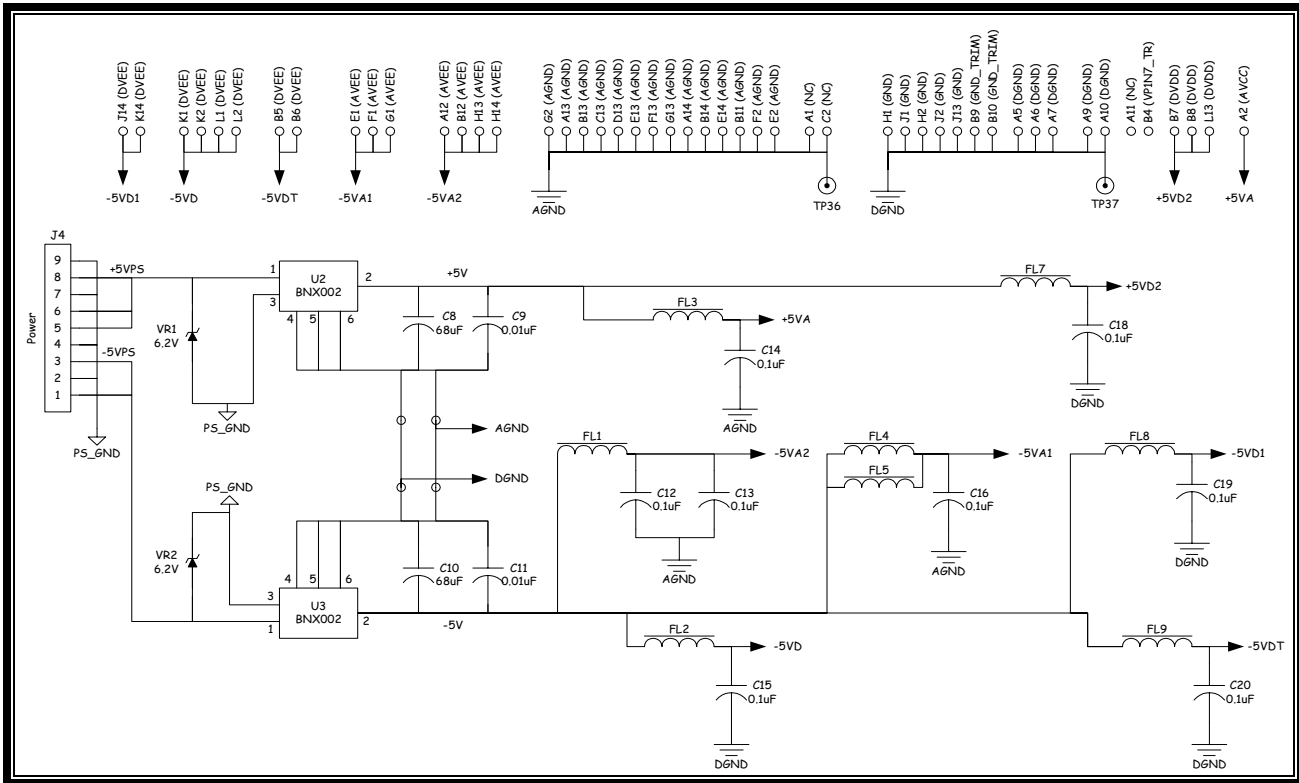


Figure 4 (Cont): TC2411 Typical Application Circuit

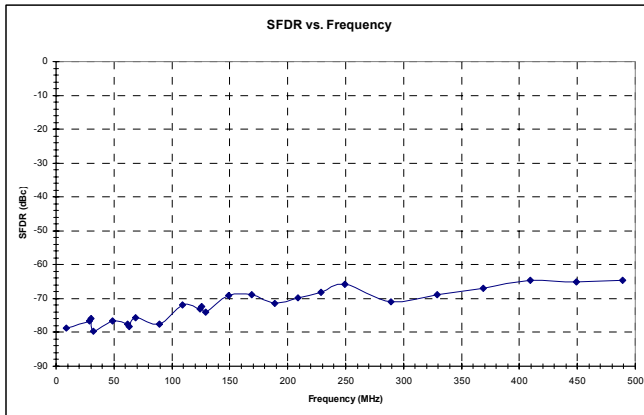


TC2411 Typical Application Circuit Parts List

| FIND # | QTY | REFERENCE DESIGNATOR | TYPE | VALUE | TOLERANCE | MANUFACTURER / DESCRIPTION |
|--------|-----|--|--------------|---------------|-----------|------------------------------------|
| 1 | 4 | C4, C5, C6, C7 | Capacitor | 1000pF | 10% | X7R |
| 2 | 3 | C3, C9, C11 | Capacitor | 0.01uF | 10% | X7R |
| 3 | 2 | C8, C10 | Capacitor | 68uF | 10% | Tantalum |
| 4 | 8 | C12, C13, C14, C15, C16, C18, C19, C20 | Capacitor | 0.1uF | 10% | X7R |
| 5 | 8 | F11, F12, F13, F14, F15, F17, F18, F19 | Ferrite Bead | BLM18A G221SN | | Murata |
| 6 | 1 | R1 | Resistor | 2.0K | 5% | |
| 7 | 1 | R4 | Resistor | 560 | 1% | |
| 8 | 1 | R5 | Resistor | 510 | 1% | |
| 9 | 1 | R6 | Resistor | 1K | 2% | |
| 10 | 1 | R7 | Resistor | 330 | 2% | |
| 11 | 1 | R8 | Resistor | 110 | 2% | |
| 12 | 1 | T1 | Transformer | TX-2-5-1 | 2% | Mini-Circuits, 2:1 impedance ratio |
| 13 | 1 | T2 | Transformer | ADT1-1WT | 2% | Mini-Circuits, 1:1 impedance ratio |
| 14 | 1 | U1 | DAC | TC2411 | | TelASIC, 14 Bit, 1GHz DAC |
| 15 | 2 | U2, U3 | EMI Filter | BNX002 | | Murata |
| 16 | 2 | VR1, VR2 | Zener | 6.2V | | 1 Watt |

TC2411 Performance Characteristics

Figure 5: SFDR vs. Frequency @ -0.5 dBFS*



* The values in Figure 1 include coax and filter losses in the setup.

Figure 6: Noise Floor vs. Frequency

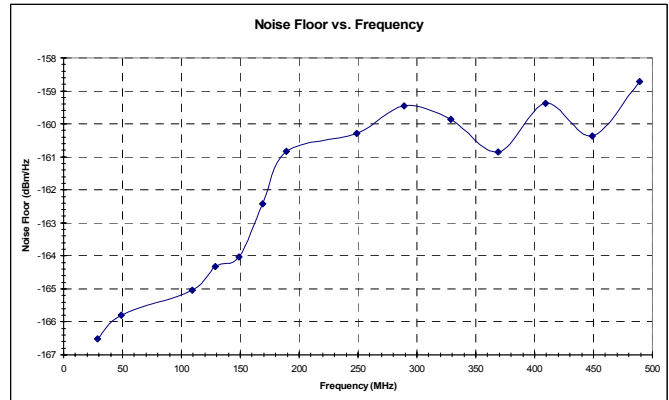


Figure 7: Clock Power Level vs. Noise

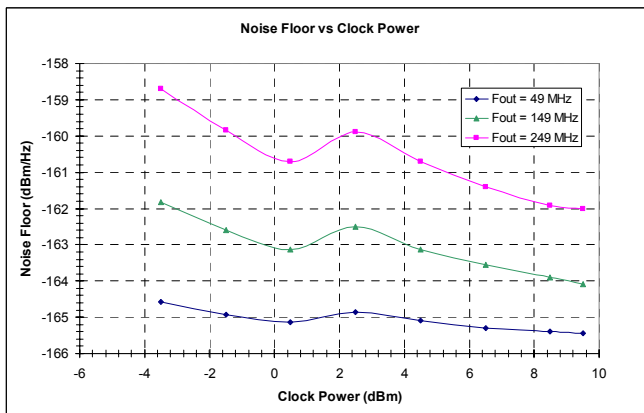


Figure 8: DAC Output Level vs. Frequency

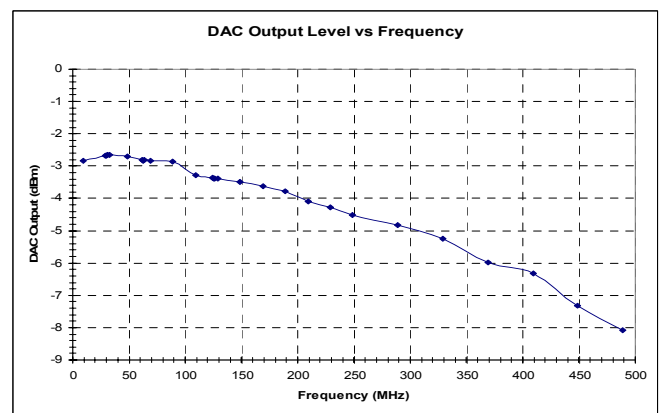


Figure 9: Two tone IMD (dBc) vs. Frequency

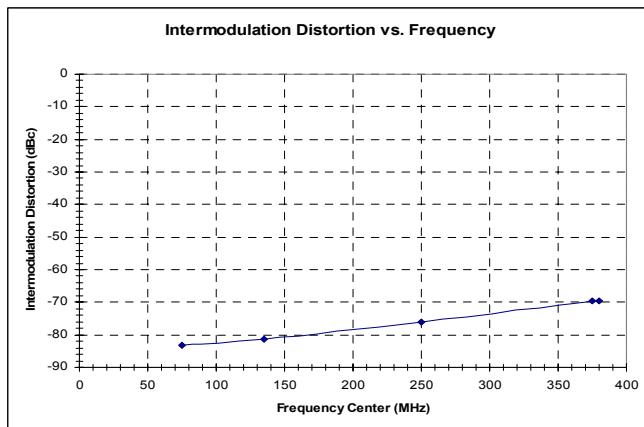


Figure 10: SFDR at 33 MHz (-77 dBc)

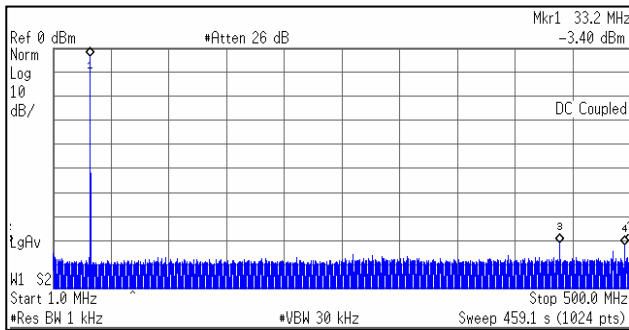


Figure 11: SFDR at 126 MHz (-75 dBc)

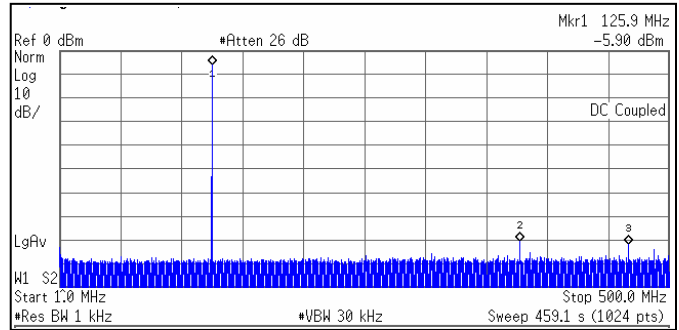


Figure 12: SFDR at 251 MHz (-72 dBc)

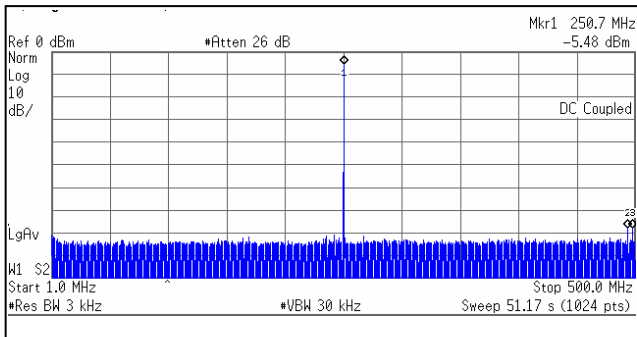


Figure 13: SFDR at 490 MHz (-61 dBc)

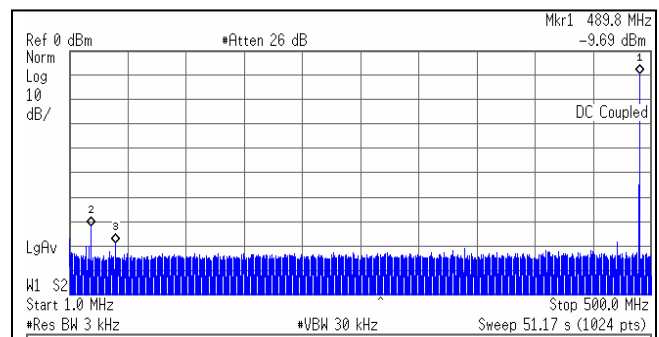


Figure 14: 2-Tone IMD (-82 dBc)*

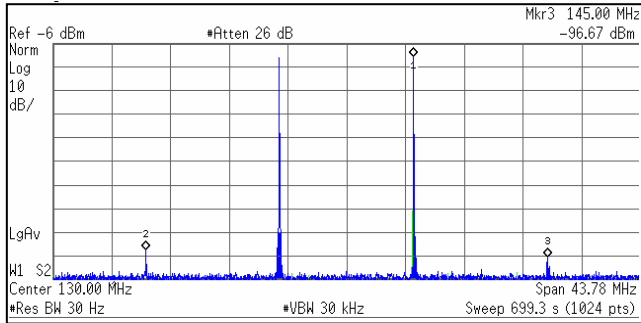


Figure 15: 4-Tone IMD (-82 dBc)*

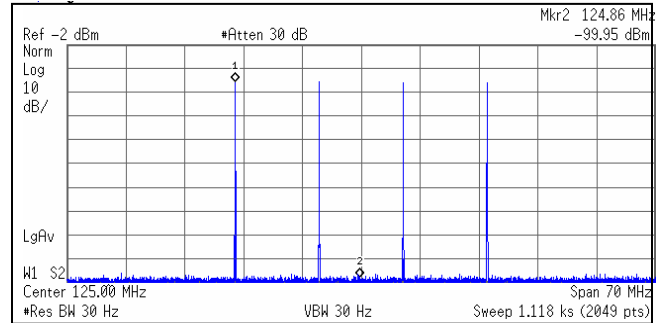
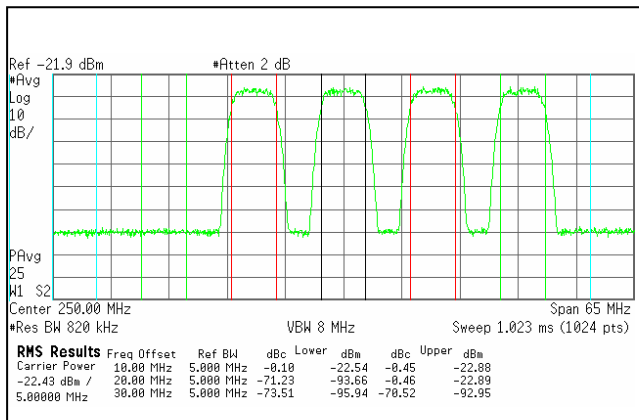


Figure 16: ACPR 4-Tone WCDMA (-76 dBc)*



* listed values indicate the actual measured levels, whereas plots shown here are limited by the instrument dynamic range

Figure 17: TC2411 Timing Diagram

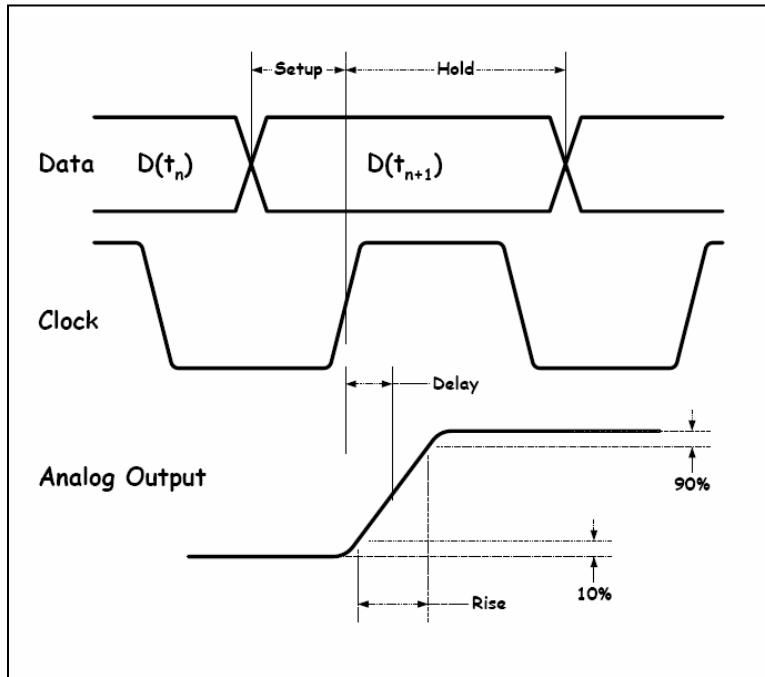


Figure 18: TC2411 Pinouts – 96 Ball Cavity-Down BGA Package (Ball Side UP)

| | 14 | 13 | 12 | 11 | 10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1 |
|---|------|------|------|------|------|------|------|------|------|------|--------------|---------|-------------|--------------|
| A | AGND | AGND | AVEE | NC | DGND | DGND | DVCC | DGND | DGND | DGND | VBB | ANODE | AVCC | AGND |
| B | AGND | AGND | AVEE | AGND | AGND | AGND | DVDD | DVDD | DVEE | DVEE | VP1N7_ TR | CATHODE | VREF_ RA | VOUT_ REF |
| C | VON | AGND | | | | | | | | | | | AGND | DNC1 |
| D | VOP | AGND | | | | | | | | | | | DNC2 | EXTCAP |
| E | AGND | AGND | | | | | | | | | | | AGND | AVEE |
| F | CLKN | AGND | | | | | | | | | | | AGND | AVEE |
| G | CLKP | AGND | | | | | | | | | | | AGND | AVEE |
| H | AVEE | AVEE | | | | | | | | | | | DGND | DGND |
| J | DVEE | DGND | | | | | | | | | | | DGND | DGND |
| K | DVEE | DVCC | | | | | | | | | | | DVEE | DVEE |
| L | SLP | DVDD | | | | | | | | | | | DVEE | DVEE |
| M | SLN | DNC3 | | | | | | | | | | | DVCC | RST |
| N | D0P | D1P | D2P | D3P | D4P | D5P | D6P | D7P | D8P | D9P | D10P | D11P | D12P | D13P |
| P | D0N | D1N | D2N | D3N | D4N | D5N | D6N | D7N | D8N | D9N | D10N | D11N | D12N | D13N |

TC2411 I/O Descriptions

| PIN | NAME | DESCRIPTION | PIN | NAME | DESCRIPTION |
|-----|----------|---------------------------------|-----|------|--------------------------------------|
| A1 | AGND | ANALOG GND | N1 | D13P | DATA INPUT BIT 13 (MSB) |
| A2 | AVCC | +5V REF AMP SUPPLY | N2 | D12P | DATA INPUT BIT 12 |
| A3 | ANODE | ANODE FOR TEMPERATURE DIODE | N3 | D11P | DATA INPUT BIT 11 |
| A4 | VBB | +2.4V Bias | N4 | D10P | DATA INPUT BIT 10 |
| A5 | DGND | DIGITAL GND | N5 | D9P | DATA INPUT BIT 9 |
| A6 | DGND | DIGITAL GND | N6 | D8P | DATA INPUT BIT 8 |
| A7 | DGND | DIGITAL GND | N7 | D7P | DATA INPUT BIT 7 |
| A8 | DVCC | +3.3V SUPPLY FOR ESD | N8 | D6P | DATA INPUT BIT 6 |
| A9 | DGND | DIGITAL GND | N9 | D5P | DATA INPUT BIT 5 |
| A10 | DGND | DIGITAL GND | N10 | D4P | DATA INPUT BIT 4 |
| A11 | NC | NO CONNECT | N11 | D3P | DATA INPUT BIT 3 |
| A12 | AVNS | -5V ANALOG SUPPLY | N12 | D2P | DATA INPUT BIT 2 |
| A13 | AGND | ANALOG GND | N13 | D1P | DATA INPUT BIT 1 |
| A14 | AGND | ANALOG GND | N14 | D0P | DATA INPUT BIT 0 (LSB) |
| B1 | VOUT_REF | VOLTAGE REFERENCE OUTPUT, +2.5V | P1 | D13N | DATA INPUT BIT 13 – COMPLEMENT (MSB) |
| B2 | VREF_RA | REFAMP INPUT | P2 | D12N | DATA INPUT BIT 12 – COMPLEMENT |
| B3 | CATHODE | CATHODE FOR TEMPERATURE DIODE | P3 | D11N | DATA INPUT BIT 11 – COMPLEMENT |
| B4 | VP1N7_TR | -1.7V TEST POINT | P4 | D10N | DATA INPUT BIT 10 – COMPLEMENT |
| B5 | DVEE | -5V SUPPLY | P5 | D9N | DATA INPUT BIT 9 – COMPLEMENT |
| B6 | DVEE | -5V SUPPLY | P6 | D8N | DATA INPUT BIT 8 – COMPLEMENT |
| B7 | DVDD | +5V DIGITAL SUPPLY | P7 | D7N | DATA INPUT BIT 7 – COMPLEMENT |
| B8 | DVDD | +5V DIGITAL SUPPLY | P8 | D6N | DATA INPUT BIT 6 – COMPLEMENT |
| B9 | AGND | ANALOG GND | P9 | D5N | DATA INPUT BIT 5 – COMPLEMENT |
| B10 | AGND | ANALOG GND | P10 | D4N | DATA INPUT BIT 4 – COMPLEMENT |
| B11 | AGND | ANALOG GND | P11 | D3N | DATA INPUT BIT 3 – COMPLEMENT |
| B12 | AVEE | -5V ANALOG SUPPLY | P12 | D2N | DATA INPUT BIT 2 – COMPLEMENT |
| B13 | AGND | ANALOG GND | P13 | D1N | DATA INPUT BIT 1 – COMPLEMENT |
| B14 | AGND | ANALOG GND | P14 | D0N | DATA INPUT BIT 0 – COMPLEMENT (LSB) |
| C1 | DNC1 | DO NOT CONNECT | H1 | DGND | DIGITAL GND |
| C2 | AGND | ANALOG GND | H2 | DGND | DIGITAL GND |
| C13 | AGND | ANALOG GND | H13 | AVEE | -5V ANALOG SUPPLY |
| C14 | VON | DAC ANALOG OUPUT – COMPLEMENT | H14 | AVEE | -5V ANALOG SUPPLY |
| D1 | EXTCAP | REF AMP BYPASS CAPACITOR | J1 | DGND | DIGITAL GND |
| D2 | DNC2 | DO NOT CONNECT | J2 | DGND | DIGITAL GND |
| D13 | AGND | ANALOG GND | J13 | DGND | DIGITAL GND |
| D14 | VOP | DAC ANALOG OUPUT | J14 | DVEE | -5V DIGITAL SUPPLY |
| E1 | AVEE | -5V ANALOG SUPPLY | K1 | DVEE | -5V DIGITAL SUPPLY |
| E2 | AGND | ANALOG GND | K2 | DVEE | -5V DIGITAL SUPPLY |
| E13 | AGND | ANALOG GND | K13 | DVCC | +3.3V DIGITAL SUPPLY |
| E14 | AGND | ANALOG GND | K14 | DVEE | -5V DIGITAL SUPPLY |
| F1 | AVEE | -5V ANALOG SUPPLY | L1 | DVEE | -5V DIGITAL SUPPLY |
| F2 | AGND | ANALOG GND | L2 | DVEE | -5V DIGITAL SUPPLY |
| F13 | AGND | ANALOG GND | L13 | DVDD | +5V DIGITAL SUPPLY |
| F14 | CLKN | DAC CLOCK INPUT – COMPLEMENT | L14 | SLP | STANDBY INPUT |
| G1 | AVEE | -5V ANALOG SUPPLY | M1 | RST | RESET/BURST MODE |
| G2 | AGND | ANALOG GND | M2 | DVCC | +3.3V SUPPLY FOR ESD |
| G13 | AGND | ANALOG GND | M13 | DNC3 | DO NOT CONNECT |
| G14 | CLKP | DAC CLOCK INPUT | M14 | SLN | STANDBY INPUT - COMPLEMENT |

Application Notes:**A. Power Supply Decoupling**

Add power supply decoupling nearby package pins as summarized below:

1. *AVEE* – bypass each group of pins with 0.1 μ F capacitor to AGND.
 - a. A12, B12
 - b. E1, F1, G1
 - c. H13, H14
2. *DVEE* – bypass each group of pins with 0.1 μ F capacitor to DGND.
 - a. K1, K2, L1, L2
 - b. J14, K14
 - c. B5, B6
3. *DVDD* – bypass each group of pins with 0.1 μ F capacitor to DGND.
 - a. B7, B8
 - b. L13
4. *AVCC* – bypass pin A2 with 0.1 μ F capacitor to AGND.
5. *DVCC* – bypass pins A8, M2 and K13 with 1000 pF capacitor to DGND.

B. Analog Outputs (VOP, VON)

The TC2411 supplies differential analog DAC outputs at pins VOP and VON. Each pin is internally terminated with 25 ohms to analog ground, creating an effective 50 ohm differential source. When these outputs are connected to a single-ended, 50 ohm load through a 1:1 transformer, the resulting full-scale AC swing is approximately 500 mVpp (20 mA into 25 ohms). Each DAC output may be dc-coupled to a ground-referenced load.

C. Clock Inputs (CLKP, CLKN)

To achieve excellent phase noise performance, the TC2411 requires a differential clock input with low jitter characteristics. A 2:1 transformer may be used to convert a single-ended, 50 ohm clock source and provide a 25 ohm, ac-coupled, differential drive into CLKP and CLKN. These inputs are internally biased and terminated with 12.5 ohms per side.

A very low-phase noise (low jitter) sinewave clock signal should be used for enhanced SNR performance. A sinewave oscillator featuring at least -130 dBc/Hz phase noise, above 20 KHz from the carrier is recommended. Best noise performance is achieved with clock sources capable of 1.5 Vpp or greater outputs.

D. LVDS-Compliant Digital Inputs (D0P/N to D13P/N)

The TC2411 offers an LVDS-compliant interface into the 14 bit data inputs. These inputs are differentially terminated on-chip with 100 ohms. 0000 corresponds to minus full-scale, while 3FFF represents plus full-scale.

E. Reset/Burst Mode (RST)

The TC2411 offers a burst mode capability whereby the DAC analog output can be asynchronously reset to the all zeros code (00 0000 0000 0000) irrespective of input data. Under normal operation, the RST pin should be held high at +3.3V. When a low signal (0V) is applied to RST, the DAC output resets to the all zeros code (minus full scale). Contact TelASIC sales for further information.

F. Temperature Diode (ANODE, CATHODE)

The TC2411 provides an on-chip temperature diode which may be used to monitor die temperature. Applying +5V to the anode pin and measuring the cathode node voltage into a 2K ohm load, the user can convert the resulting voltage into a temperature. Contact TelASIC sales for further information.

G. External Capacitor for Ref Amp (EXTCAP)

The on-chip reference amplifier requires an external capacitor to maintain excellent phase noise and jitter characteristics. Attach two capacitors, 0.01 uF and 1000 pF, in parallel between the EXTCAP pin and -5V analog supply.

H. Ref Amp Input (VREF_RA)

VOUT_REF is an internally generated, +2.5V precision bandgap reference. Tie this output to VREF_RA, the ref amp input.

I. Standby Mode Function (SLP, SLN)

The TC2411 offers a Standby Mode capability whereby the power dissipation is reduced to 850mW. The standby function comes in on pins L14 (SLP) and M14 (SLN). Under normal operation both pins are left floating. This mode may be enabled with either a single-ended drive or a differential drive.

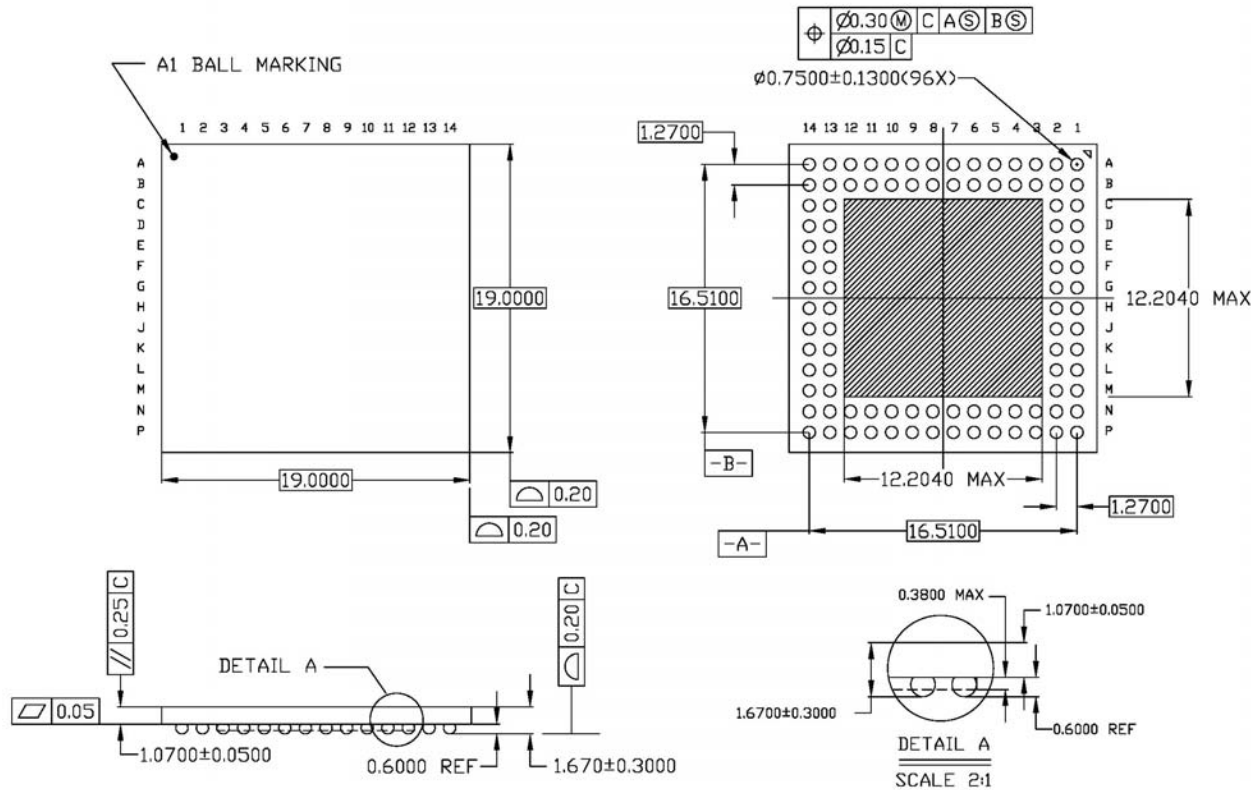
Single-ended drive, M14 (SLN) pin should be left floating and L14 (SLP) pin should be held low at +0.0V for normal operation, L14 (SLP) pin should be held high at +3.3V (CMOS) for standby mode.

Differential drive level requires external 100 ohm resistor between pins L14 (SLP) and M14 (SLN) and uses standard LVDS, (i.e. low level is 1.0V, high level is 1.4V). For normal mode M14 (SLN) is set low and L14 (SLP) is set high. For sleep mode M14 (SLN) is set high and L14 (SLP) is set low.

J. Do Not Connect Pins

Pins DNC1 (C1), DNC2 (D2), and DNC3 (M13) should be left floating. Connecting these pins to ground or to either supply voltage will alter device performance and may damage the part.

Figure 19: TC2411 96 Ball, Cavity-Down BGA Package Outline Dimensions (mm)



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